PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Nishant Sinha

Serial No.: 10/668,914

Filed: September 23, 2003

For: PROCESS AND INTEGRATION SCHEME FOR FABRICATING CONDUCTIVE COMPONENTS, THROUGH-VIAS AND SEMICONDUCTOR COMPONENTS INCLUDING CONDUCTIVE THROUGH-WAFER VIAS

Confirmation No.: 2525

Examiner: W. Lindsay Jr.

Group Art Unit: 2812

Attorney Docket No.: 2269-5859US
(02-0390.00/US)

VIA ELECTRONIC FILING
June 25, 2007

FEE ADDRESSEE FOR RECEIPT OF PTO NOTICES RELATING TO MAINTENANCE FEES

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

1. This letter is to specify that the FEE ADDRESSEE for this patent is:

MICRON TECHNOLOGY, INC.
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8000 South Federal Way
Boise, Idaho 83707-0006

2. The Customer Number for the Fee Addressee is **26809**.

3. Any prior FEE ADDRESSEE for this patent is hereby revoked.

4. It is certified that the person whose signature appears below has the authority to change the FEE ADDRESSEE for this patent.

Respectfully submitted,

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